

# SOT1980-2

FCD36, flip chip die, 36 terminals, 1.63 mm x 1.63 mm x 0.225 mm body

19 May 2020

Package information

## 1 Package summary

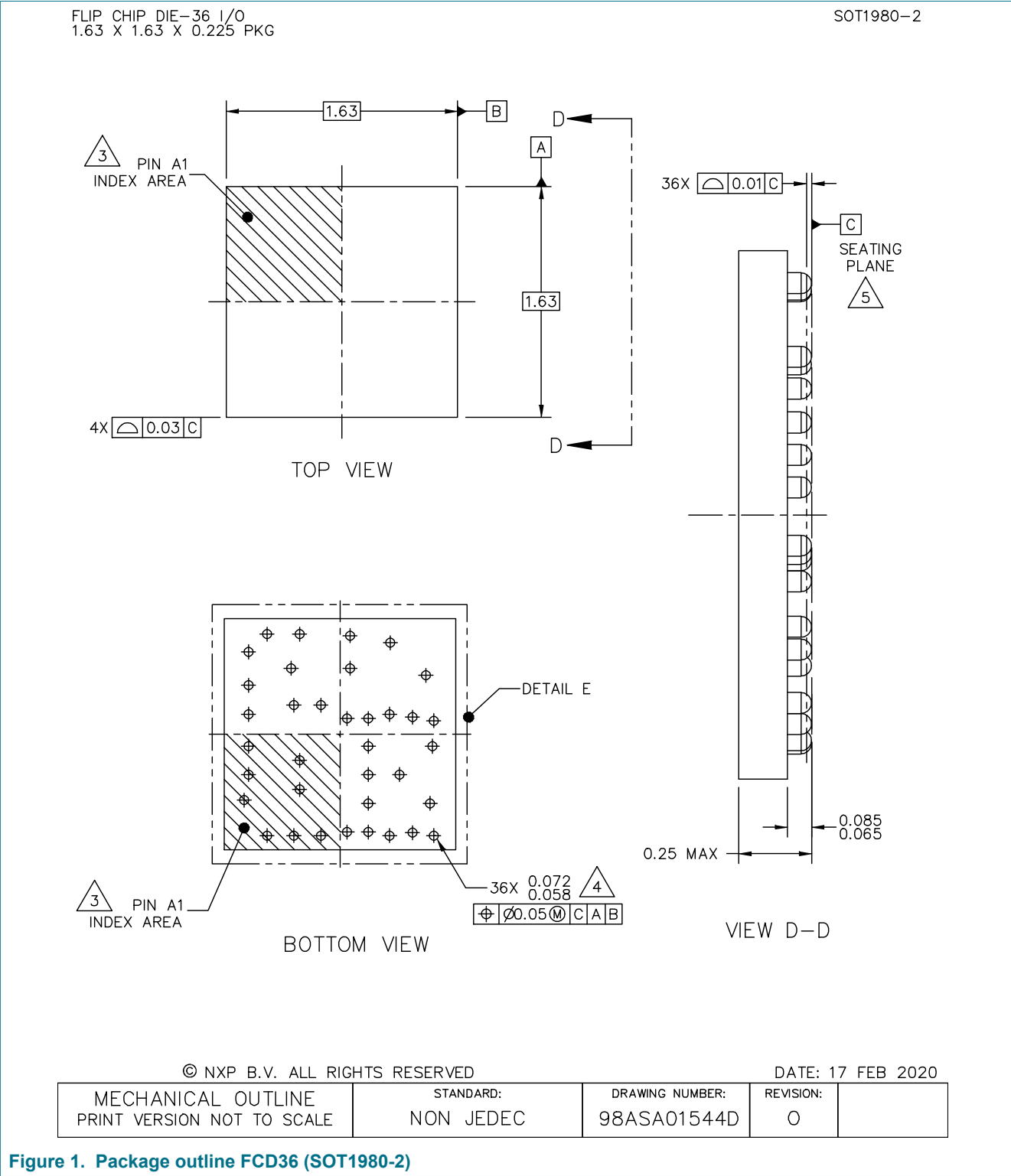
Terminal position code	B (bottom)
Package type descriptive code	FCD36
Package style descriptive code	FCD (flip chip die)
Mounting method type	S (surface mount)
Issue date	17-02-2020
Manufacturer package code	98ASA01544D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.6	1.63	1.66	mm
package width	1.6	1.63	1.66	mm
package height	-	0.225	0.25	mm
actual quantity of termination	-	36	-	

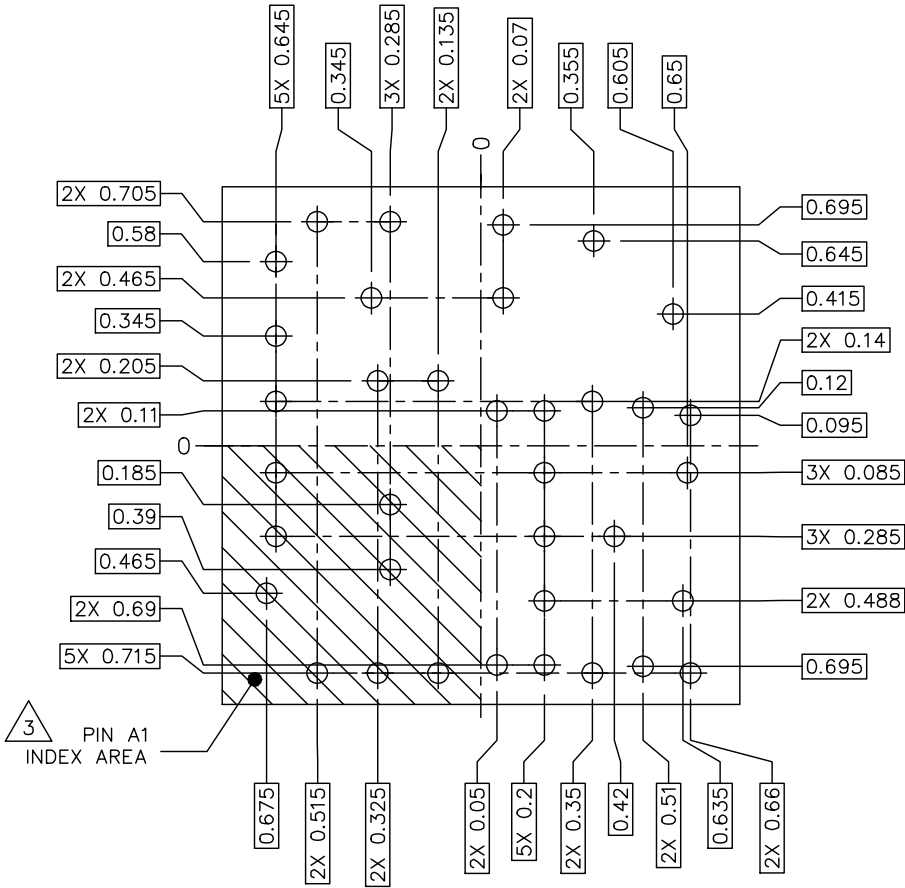


2 Package outline



FLIP CHIP DIE—36 I/O  
1.63 X 1.63 X 0.225 PKG

SOT1980-2



DETAIL E

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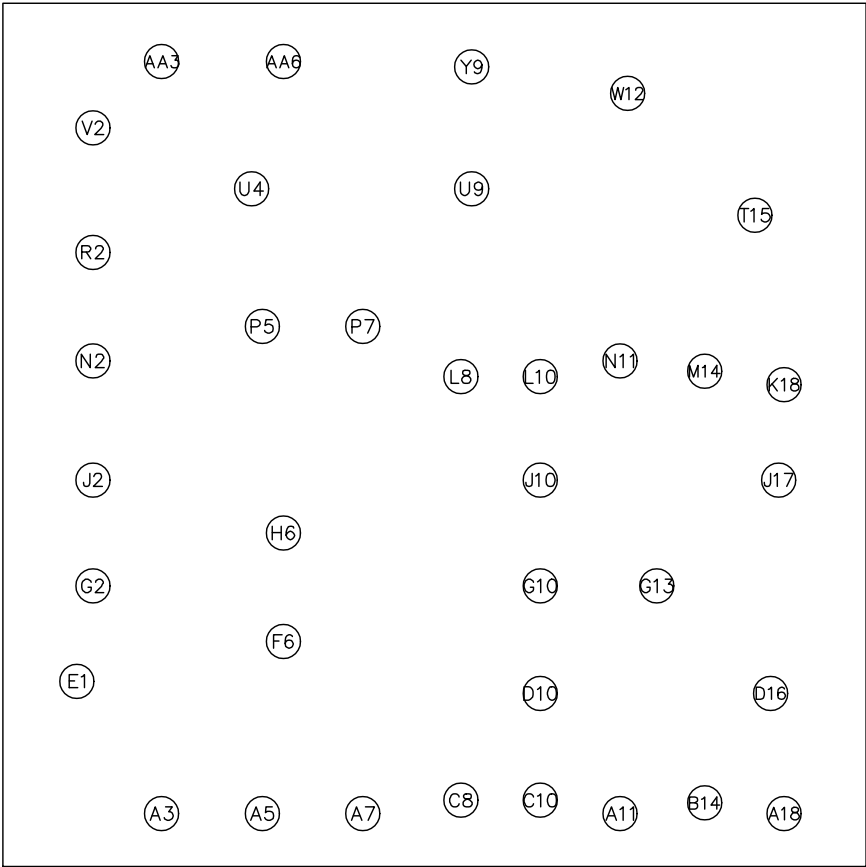
DATE: 17 FEB 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01544D	REVISION: 0	
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Figure 2. Package outline detail E of FCD36 (SOT1980-2)

FLIP CHIP DIE—36 I/O  
1.63 X 1.63 X 0.225 PKG

SOT1980—2



PIN NUMBERS  
(VIEWED FROM BOTTOM, SAME AS DETAIL E)

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Figure 3. Package outline pin numbers of FCD36 (SOT1980-2)

FLIP CHIP DIE—36 I/O  
1.63 X 1.63 X 0.225 PKG

SOT1980-2

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01544D	REVISION: 0	

Figure 4. Package outline note FCD36 (SOT1980-2)

### 3 Legal information

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